



US00D584250S

(12) **United States Design Patent**  
**Tani et al.**

(10) **Patent No.:** **US D584,250 S**  
(45) **Date of Patent:** **\*\* Jan. 6, 2009**

(54) **GROOVES FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/303,707**

(22) Filed: **Feb. 15, 2008**

**Related U.S. Application Data**

(62) Division of application No. 29/268,261, filed on Nov. 1, 2006, now Pat. No. Des. 567,774.

(30) **Foreign Application Priority Data**

May 1, 2006 (JP) ..... 2006-011443  
May 1, 2006 (JP) ..... 2006-011445  
May 1, 2006 (JP) ..... 2006-011446

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
174/250, 251, 253, 254, 255, 256, 265, 260,  
174/261; 361/760, 748, 720; 336/200  
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for grooves formed around a semiconductor device on a circuit board, as shown and described.

**DESCRIPTION**

FIG. 1 shows a plan view of the grooves formed around a semiconductor on a circuit board showing the design according to the invention.

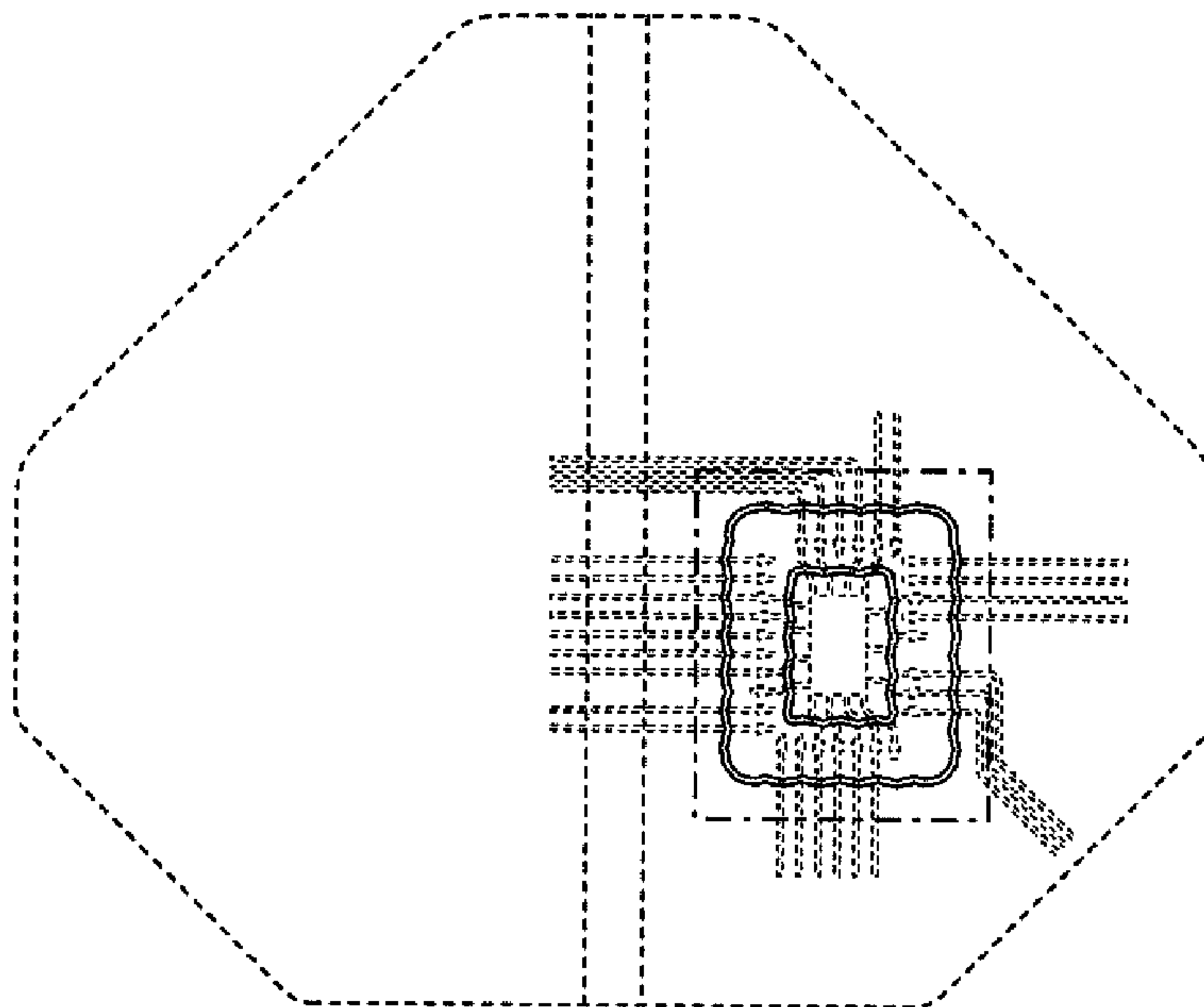
FIG. 2 shows an enlarged view of a claimed portion as identified by the area boxed by the dash-dot-dash line in FIG. 1.

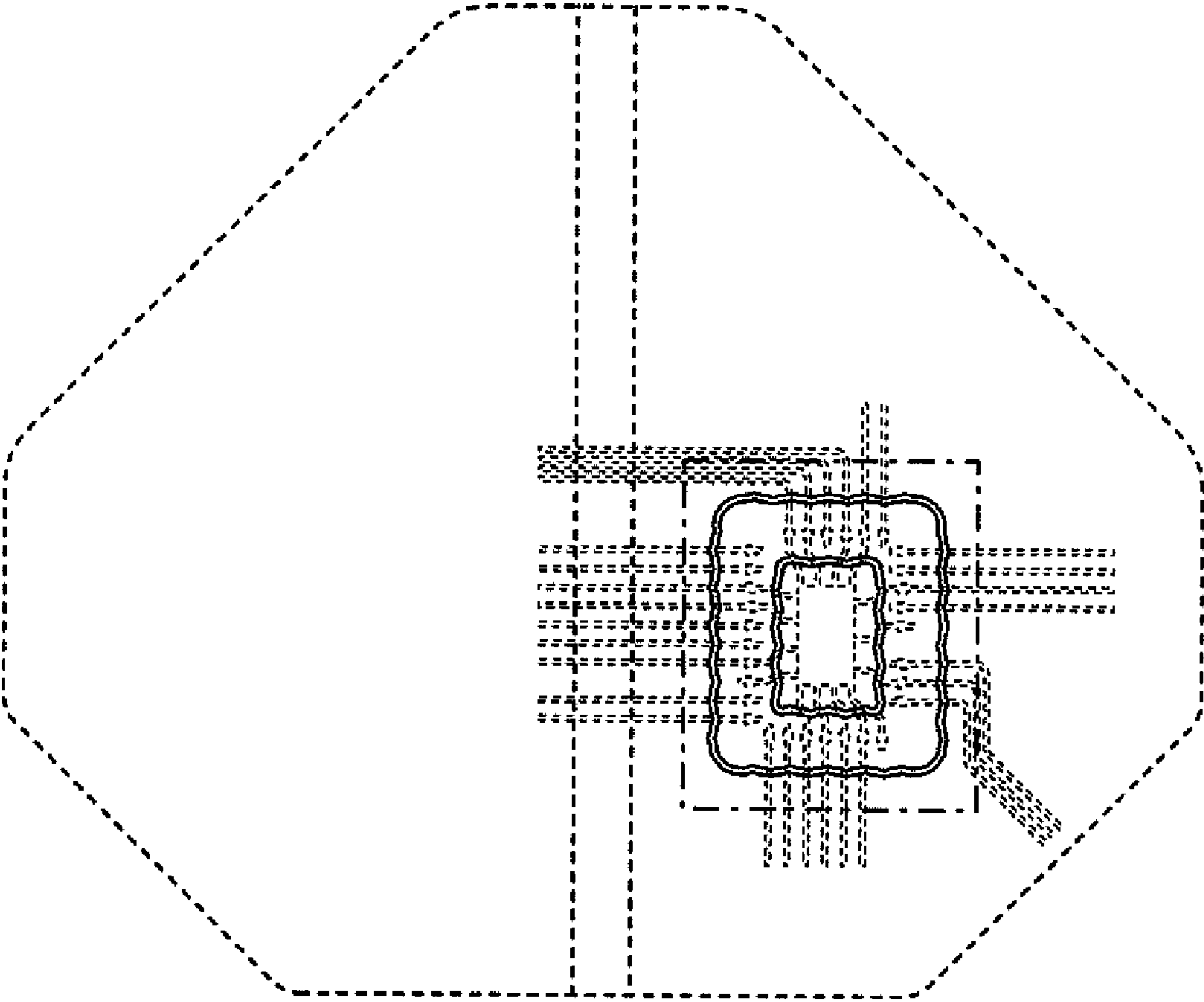
FIG. 3 shows an enlarged sectional view along the line 3—3 in FIG. 2; and,

FIG. 4 shows an enlarged sectional view along the line 4—4 in FIG. 2.

The elements shown in broken lines and dash-dot-dash lines are for illustrative purposes only and form no part of the claimed invention.

**1 Claim, 2 Drawing Sheets**





**FIG. 1**

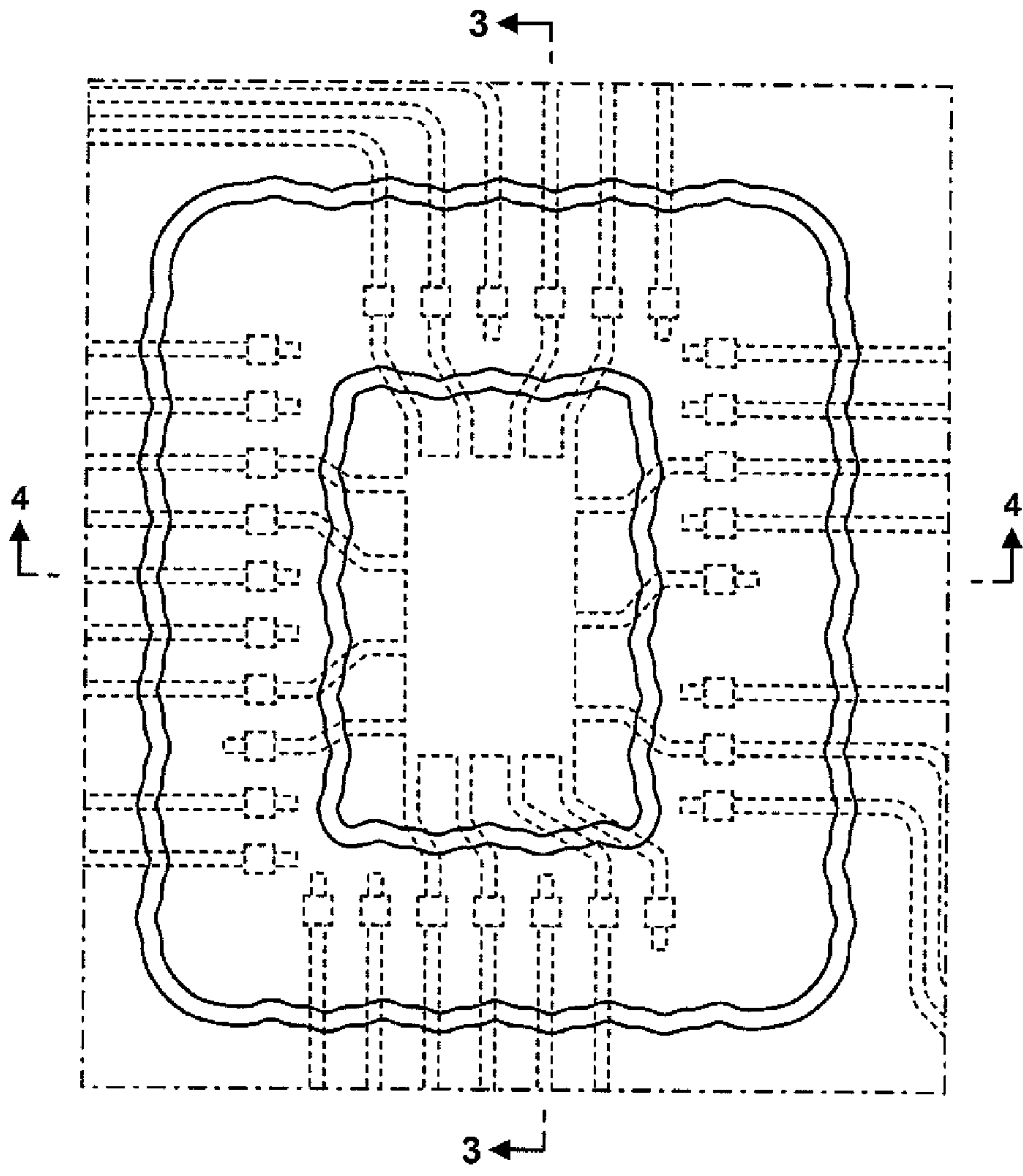


FIG. 2



FIG. 3

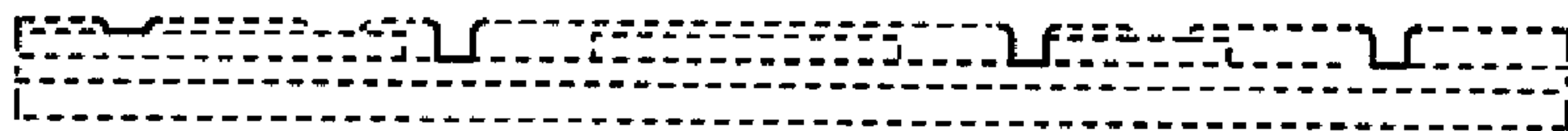


FIG. 4